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PATENT APPLICATION

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re application of

Docket No: Q92997

Yasukazu NAKATA, et al.

Appln. No.: 10/567,358

Group Art Unit: 2835

Confirmation No.: 9855

Examiner: Not Yet Assigned

Filed: February 6, 2006

For: FLIP CHIP MOUNTING SUBSTRATE

REQUEST FOR CORRECTED OFFICIAL FILING RECEIPT

ATTN: Office of Initial Patent Examination
Filing Receipt Correction
Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450

Sir:

We enclose a copy of the Official Filing Receipt for the above-identified application and request the following correction:

Assignment for Published Patent Application

LINTEC CORPORATION

Verification for the requested correction is indicated on the Assignment filed February 6, 2006.

Respectfully submitted,



Robert V. Sloan
Registration No. 22,775

SUGHRUE MION, PLLC
Telephone: (202) 293-7060
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WASHINGTON OFFICE
23373
CUSTOMER NUMBER

Date: July 21, 2006



UNITED STATES PATENT AND TRADEMARK OFFICE

UNITED STATES DEPARTMENT OF COMMERCE
 United States Patent and Trademark Office
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APPL NO.	FILING OR 371 (c) DATE	ART UNIT	FIL FEE REC'D	ATTY DOCKET NO	DRAWINGS	TOT CLMS	IND CLMS
10/567,358	02/06/2006	2835	900	Q92997	2	4	1

CONFIRMATION NO. 9855

23373
 SUGHRUE MION, PLLC
 2100 PENNSYLVANIA AVENUE, N.W.
 SUITE 800
 WASHINGTON, DC 20037

FILING RECEIPT



OC000000019196354

Date Mailed: 06/13/2006

Receipt is acknowledged of this regular Patent Application. It will be considered in its order and you will be notified as to the results of the examination. Be sure to provide the U.S. APPLICATION NUMBER, FILING DATE, NAME OF APPLICANT, and TITLE OF INVENTION when inquiring about this application. Fees transmitted by check or draft are subject to collection. Please verify the accuracy of the data presented on this receipt. If an error is noted on this Filing Receipt, please mail to the Commissioner for Patents P.O. Box 1450 Alexandria Va 22313-1450. Please provide a copy of this Filing Receipt with the changes noted thereon. If you received a "Notice to File Missing Parts" for this application, please submit any corrections to this Filing Receipt with your reply to the Notice. When the USPTO processes the reply to the Notice, the USPTO will generate another Filing Receipt incorporating the requested corrections (if appropriate).

Applicant(s)

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 Katsuyoshi Matsuura, Tokyo, JAPAN;

Taiga Matsushita, Tokyo, JAPAN;

Assignment for Published Patent Application
LINTEC CORPORATION

Power of Attorney: The patent practitioners associated with Customer Number 23373.

Domestic Priority data as claimed by applicant

This application is a 371 of PCT/JP04/11279 07/30/2004

Foreign Applications

JAPAN 2003-206098 08/05/2003

If Required, Foreign Filing License Granted: 06/08/2006

The country code and number of your priority application, to be used for filing abroad under the Paris Convention, is **US10/567,358**

Projected Publication Date: 09/14/2006

Non-Publication Request: No

Early Publication Request: No

Title

Flip chip mounting substrate

Preliminary Class

361

PROTECTING YOUR INVENTION OUTSIDE THE UNITED STATES

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Applicants may wish to consult the USPTO booklet, "General Information Concerning Patents" (specifically, the section entitled "Treaties and Foreign Patents") for more information on timeframes and deadlines for filing foreign patent applications. The guide is available either by contacting the USPTO Contact Center at 800-786-9199, or it can be viewed on the USPTO website at <http://www.uspto.gov/web/offices/pac/doc/general/index.html>.

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Assignment

Whereas, I/We,

NAKATA Yasukazu of c/o LINTEC Corporation, 23 – 23, Honcho, Itabashi – ku, Tokyo, 173 – 0001 Japan

MATSUURA Katsuyoshi of c/o LINTEC Corporation, 23 – 23, Honcho, Itabashi – ku, Tokyo, 173 – 0001 Japan

MATSUSHITA Taiga of c/o LINTEC Corporation, 23 – 23, Honcho, Itabashi – ku, Tokyo, 173 – 0001 Japan

hereinafter called assignor(s), have invented certain improvements in

FLIP CHIP MOUNTING SUBSTRATE

and executed an application for Letters Patent of the United States of America therefor on

January 19, 2006 ; and

Whereas,

LINTEC Corporation of 23 – 23, Honcho, Itabashi – ku, Tokyo, 173 – 0001 Japan

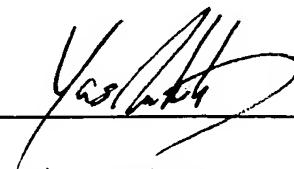
(assignee), desires to acquire the entire right, title, and interest in the application and invention, and to any United States patents to be obtained therefor;

Now therefore, for valuable consideration, receipt whereof is hereby acknowledged,

I/We, the above named assignor(s), hereby sell, assign and transfer to the above named assignee, its successors and assigns, the entire right, title and interest in the application and the invention disclosed therein for the United States of America, including the right to claim priority under 35 U.S.C. §119, and I/we request the Commissioner of Patents to issue any Letters Patent granted upon the invention set forth in the application to the assignee, its successors and assigns; and I/we will execute without further consideration all papers deemed necessary by the assignee in connection with the United States application when called upon to do so by the assignee.

I/We hereby authorize and request my attorneys SUGHRUE, MION, ZINN, MACPEAK & SEAS of 2100 Pennsylvania Avenue, N.W., Washington, D.C. 20037-3202 to insert here in parentheses (Application number _____, filed _____) the filing date and application number of said application when known.

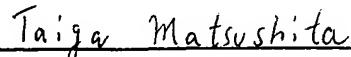
Date: 19/01/2006 s/ NAKATA Yasukazu



Date: 19/01/2006 s/ MATSUURA Katsuyoshi



Date: 19/01/2006 s/ MATSUSHITA Taiga



Date: s/ _____

Date: s/ _____